

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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CREE™ XP® ADHESIVE-BACKED LENS SYSTEM



OPERATING CONDITIONS

▲ -40°C to +110°C temperature

FEATURES / BENEFITS

- ▲ For CREE XPE & XPC LEDs
- ▲ Available in spot, medium, wide, frosted spot and oval lenses
- ▲ Integral self-adhesive pad
- ▲ Compact size
- ▲ Greater than 80% efficiency
- ▲ 3 alignment tabs to ensure accurate placement over LED
- ▲ Frosted model for even light output within 7° half divergence & smooth tailoff. Designed to minimize hot spots & fringing in color mixing applications

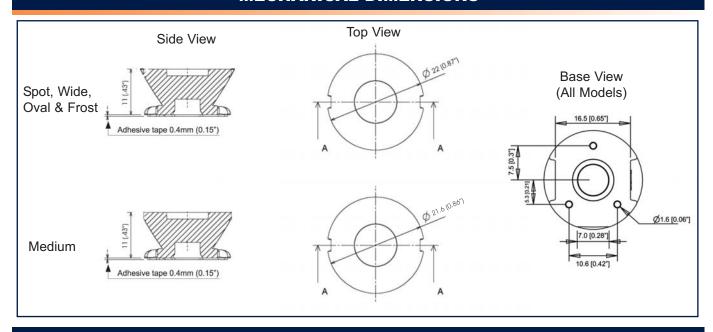
MATERIALS/FINISH

▲ Optical grade polycarbonate 143R

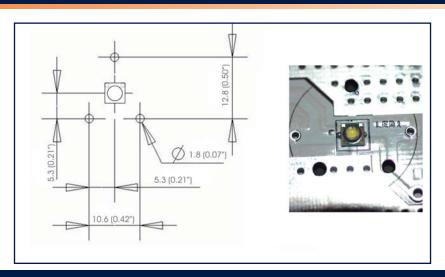
ORDERING INFORMATION

BASE LENSES		
Dialight P/N	Description	Degree*
OPXP1SPOT	Spot Base Module for CREE XPE & XPC	5°
OPXP1SDIF	Diffused Spot Base Module for CREE XPE & XPC	7°
OPXP1MDIF	Medium Diffused Base Module for CREE XPE & XPC	10°
OPXP1 OVAL	Oval Base Module for CREE XPE & XPC	8° X 25°
OPXP1WIDE	Wide Diffused Base Module for CREE XPE & XPC	20°
*All angles refer to half divergence		

MECHANICAL DIMENSIONS



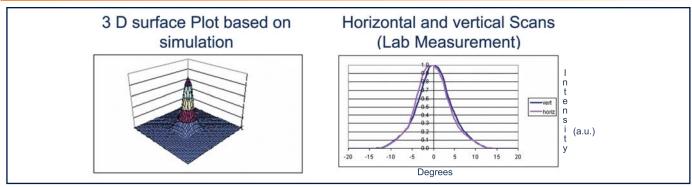
PCB ALIGNMENT DIMENSION DETAILS







PHOTOMETRIC DATA FOR SPOT VERSION



For photometric data on other models, please contact factory

Dialight reserves the right to make changes at any time in order to supply the best product possible.

The most current version of this document will always be available at:

www.dialight.com/Assets/Brochures_And_Catalogs/Illumination/MDEXLUMADBCREEXP.pdf